Regarding the change of names mentioned in the document, such as Mitsubishi Electric and Mitsubishi XX, to Renesas Technology Corp.

The semiconductor operations of Hitachi and Mitsubishi Electric were transferred to Renesas Technology Corporation on April 1st 2003. These operations include microcomputer, logic, analog and discrete devices, and memory chips other than DRAMs (flash memory, SRAMs etc.) Accordingly, although Mitsubishi Electric, Mitsubishi Electric Corporation, Mitsubishi Semiconductors, and other Mitsubishi brand names are mentioned in the document, these names have in fact all been changed to Renesas Technology Corp. Thank you for your understanding. Except for our corporate trademark, logo and corporate statement, no changes whatsoever have been made to the contents of the document, and these changes do not constitute any alteration to the contents of the document itself.

Note: Mitsubishi Electric will continue the business operations of high frequency & optical devices and power devices.

Renesas Technology Corp. Customer Support Dept. April 1, 2003





16-BIT CMOS MICROCOMPUTER

DESCRIPTION

The M37735S4BFP is a microcomputer using the 7700 Family core. This microcomputer has a CPU and a bus interface unit. The CPU is a 16-bit parallel processor that can be an 8-bit parallel processor, and the bus interface unit enhances the memory access efficiency to execute instructions fast. This microcomputer also includes a 32 kHz oscillation circuit, in addition to the RAM, multiple-function timers, serial I/O, A-D converter, and so on.

FEATURES

Number of basic	instructions	103
■Memory size	RAM	2048 bytes
■Instruction execu	ition time	
The fastest instru	uction at 25 MHz frequency	160 ns
●Single power sup	oply	5 V ± 10%
Low power dissip	pation (at 25 MHz frequency)	
		47.5 mW (Typ.
●Interrupts		19 types, 7 levels
Multiple-function	16-bit timer	5 + 3
Serial I/O (UART	or clock synchronous)	

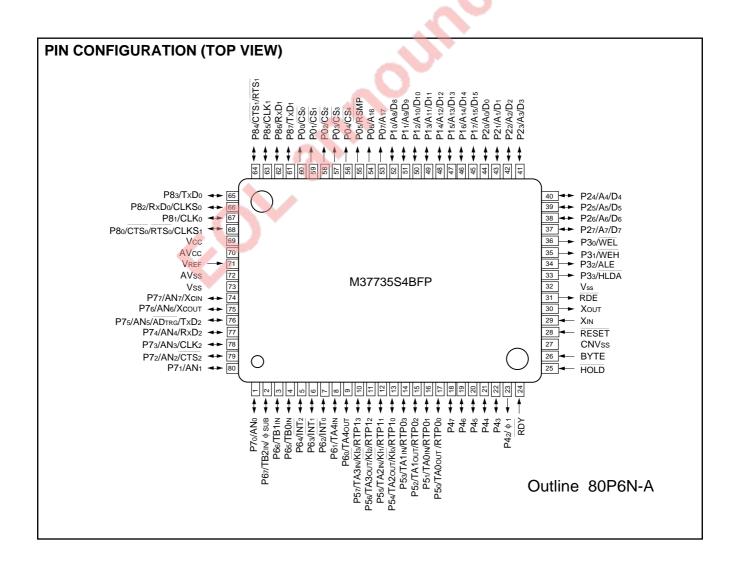
●10-bit A-D	converte	r8-channel inputs

●12-bit watchdog timer

APPLICATION

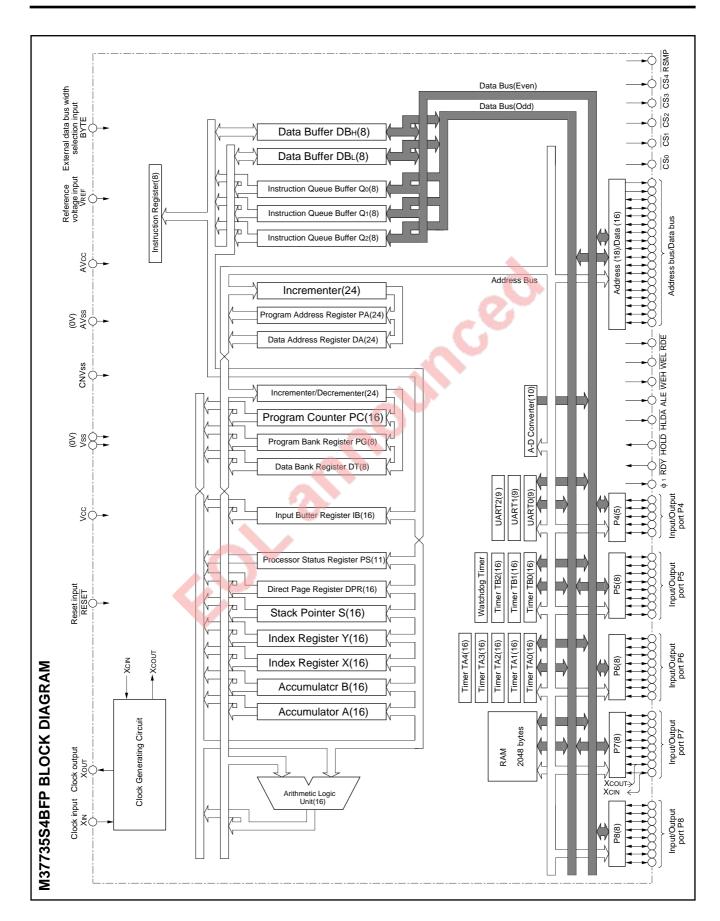
Control devices for general commercial equipment such as office automation, office equipment, and so on.

Control devices for general industrial equipment such as communication equipment, and so on.













16-BIT CMOS MICROCOMPUTER

FUNCTIONS OF M37735S4BFP

	Parameter	Functions			
Number of basic instructions		103			
Instruction execution time		160ns (the fastest instruction at external clock 25 MHz frequency)			
Memory size	RAM	2048 bytes			
Input/Output ports	P5 – P8	8-bit X 4			
input output porto	P4	5-bit X 1			
Multi-function timers	TA0, TA1, TA2, TA3, TA4	16-bit X 5			
wuiti-turiction timers	TB0, TB1, TB2	16-bit X 3			
Serial I/O	·	(UART or clock synchronous serial I/O) X 3			
A-D converter		10-bit X 1 (8 channels)			
Watchdog timer		12-bit X 1			
Interrupte		3 external types, 16 internal types			
Interrupts		Each interrupt can be set to the priority level $(0 - 7.)$			
Clock generating circuit		2 circuits built-in (externally connected to a ceramic resonator or a quartz-crystal oscillator)			
Supply voltage		5 V ± 10%			
Power dissipation		47.5 mW (at external clock 25 MHz frequency)			
Input/Output characteristic	Input/Output voltage	5 V			
input/Output characteristic	Output current	5 mA			
Memory expansion	•	Maximum 1 Mbytes			
Operating temperature range)	−20 to 85 °C			
Device structure		CMOS high-performance silicon gate process			
Package		80-pin plastic molded QFP (80P6N-A)			





16-BIT CMOS MICROCOMPUTER

PIN DESCRIPTION

Pin	Name	Input/Output	Functions
Vcc,	Power source		Apply 5 V \pm 10% to Vcc and 0 V to Vss.
Vss			
CNVss	CNVss input	Input	Connect to Vcc.
RESET	Reset input	Input	When "L" level is applied to this pin, the microcomputer enters the reset state.
XIN	Clock input	Input	These are pins of main-clock generating circuit. Connect a ceramic resonator or a quartz-crystal oscillator between XIN and XOUT. When an external clock is used, the clock source should be
Хоит	Clock output	Output	connected to the XIN pin, and the XOUT pin should be left open.
RDE	Read enable output	Output	When data/instruction read is performed, output level of RDE signal is "L".
BYTE	Bus width selection input	Input	This pin determines whether the external data bus has an 8-bit width or a 16-bit width. The data bus has a 16-bit width when "L" signal is input and an 8-bit width when "H" signal is input.
AVcc,	Analog power		Power source input pin for the A-D converter. Externally connect AVcc to Vcc and AVss to Vss.
AVss	source input	1	This is not an example as insulation (south a A.D. as a control
VREF	Reference voltage input	Input	This is reference voltage input pin for the A-D converter.
P00/CS ₀ – P04/CS ₄	Chip selection output	Output	When the specified external memory area is accessed, $\overline{CS_0}$ – $\overline{CS_4}$ signals are "L".
P05/RSMP	Ready sampling output	Output	The timing signal to be input to the RDY pin is output.
P06/A16, P07/A17	Address output	Output	An address (A ₁₆ , A ₁₇) is output.
P10/A8/D8 -	Address output	I/O	When the BYTE pin is set to "L" and external data bus has a 16-bit width, high-order data
P17/A15/D15	/data (high -order) I/O		(D ₈ – D ₁₅) is input/output or an address (A ₈ – A ₁₅) is output. When the BYTE pin is "H" and an external data bus has an 8-bit width, only address (A ₈ – A ₁₅) is output.
P20/A0/D0-	Address output	I/O	Low-order data (Do - D7) is input/output or an address (Ao - A7) is output.
P27/A7/D7	/data (low -order) I/O		
P30/WEL	Write enable output	Output	When the BYTE pin is "L" and writing to an even address is performed, output level of WEL signal is "L". When the BYTE pin is "H" and writing to an even address or an odd address is performed, output level of WEL signal is "L".
P31/WEH	Write enable high output	Output	When the BYTE pin is "L" and writing to an odd address is performed, output level of WEH signal is "L". When the BYTE pin is "H", WEH signal is always "H".
P32/ALE	Address latch enable output	Output	This is used to retrieve only the address from the multiplex signal which consists of address and data.
P33/HLDA	Hold acknow- ledge output	Output	This outputs "L" level when the microcomputer enters hold state after a hold request is accepted.
HOLD	Hold request input	Input	This is an input pin for HOLD request signal. The microcomputer enters hold state while this signal is "L".
RDY	Ready input	Input	This is an input pin for RDY signal. The microcomputer enters ready state while this signal is "L".
P42/ ф 1	Clock output	Output	This pin outputs the clock \$\phi\$ 1.
P43 – P47	I/O port P4	I/O	These pins become a 5-bit I/O port. An I/O direction register is available so that each pin can be programmed for input or output. These ports are in the input mode when reset.
P50 – P57	I/O port P5	I/O	In addition to having the same functions as port P4, these pins also function as I/O pins for timers A0 to A3 and input pins for key input interrupt input (KI ₀ – KI ₃).
P60 – P67	I/O port P6	I/O	In addition to having the same functions as port P4, these pins also function as I/O pins for timer A4, input pins for external interrupt input $(\overline{INT_0} - \overline{INT_2})$ and input pins for timers B0 to B2. P67 also functions as sub-clock ϕ SUB output pin.
P70 – P77	I/O port P7	I/O	In addition to having the same functions as port P4, these pins function as input pins for A-D converter. P72 to P75 also function as I/O pins for UART2. Additionally, P76 and P77 have the function as the output pin (XCOUT) and the input pin (XCN) of the sub-clock (32 kHz) oscillation circuit, respectively. When P76 and P77 are used as the XCOUT and XCIN pins, connect a resonator or an oscillator between the both.
P80 – P87	I/O port P8	I/O	In addition to having the same functions as port P4, these pins also function as I/O pins for UART 0 and UART 1.





16-BIT CMOS MICROCOMPUTER

BASIC FUNCTION BLOCKS

The M37735S4BFP has the same functions as the M37735MHBXXXFP except for the following:

- (1) The memory map is different.
- (2) The processor mode is different.
- (3) The reset circuit is different.
- (4) Pulse output port mode of timer A is available.
- (5) The function of ROM area modification is not available.

Refer to the section on the M37735MHBXXXFP, except for above (1)–(5).

MEMORY

The memory map is shown in Figure 1. The address space has a capacity of 16 Mbytes and is allocated to addresses from 016 to FFFFFF16. The address space is divided by 64-Kbyte unit called bank. The banks are numbered from 016 to FF16.

However, banks 1016-FF16 of the M37735S4BFP cannot be accessed.

Built-in RAM and control registers for internal peripheral devices are assigned to bank 016.

Addresses FFD616 to FFFF16 are the RESET and interrupt vector addresses and contain the interrupt vectors. Use ROM for memory of this address.

The 2048-byte area allocated to addresses from 8016 to 87F16 is the built-in RAM. In addition to storing data, the RAM is used as stack during a subroutine call or interrupts.

Peripheral devices such as I/O ports, A-D converter, serial I/O, timer, and interrupt control registers are allocated to addresses from 0₁₆ to 7F₁₆.

A 256-byte direct page area can be allocated anywhere in bank 016 by using the direct page register (DPR). In the direct page addressing mode, the memory in the direct page area can be accessed with two words. Hence program steps can be reduced.

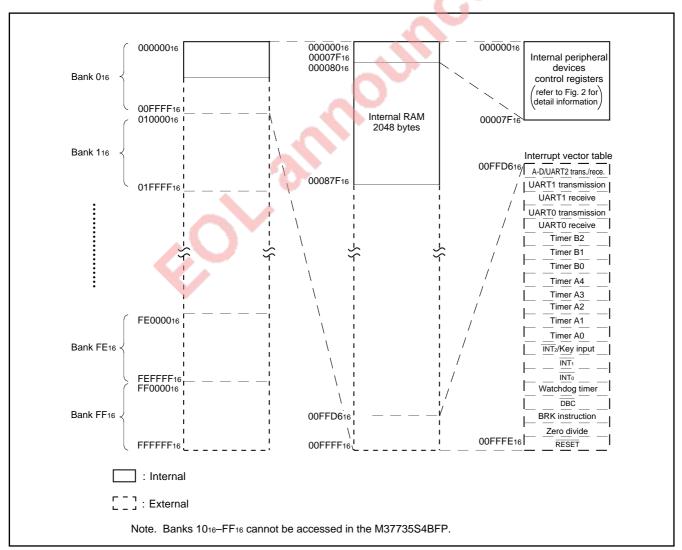


Fig. 1 Memory map





16-BIT CMOS MICROCOMPUTER

•	adecimal notation)	`	adecimal notation)
000000		000040	Count start flag
000001	Port P0 register	000041 000042	One-shot start flag
000002	Port P1 register	000042	One-shot start hag
000003	Port P0 direction register	000043	Up-down flag
000005	Port P1 direction register	000044	op down nag
000006	Port P2 register	000046	
000007	Port P3 register	000047	Timer A0 register
800000	Port P2 direction register	000048	
000009	Port P3 direction register	000049	Timer A1 register
A0000	Port P4 register	00004A	Time AQ and inter-
0000B	Port P5 register	00004B	Timer A2 register
0000C	Port P4 direction register	00004C	Timer A3 register
0000D	Port P5 direction register	00004D	Timer A3 register
0000E	Port P6 register	00004E	Timer A4 register
0000F	Port P7 register	00004F	Timor 74 register
00010	Port P6 direction register	000050	Timer B0 register
00011	Port P7 direction register	000051	
00012	Port P8 register	000052	Timer B1 register
00013	Deat DO discretical register	000053	
00014	Port P8 direction register	000054	Timer B2 register
00015		000055	Timer A0 mode register
00016 00017		000056 000057	Timer A1 mode register Timer A1 mode register
00017		000057	Timer A2 mode register
00018		000059	Timer A3 mode register
00019 0001A		000059 00005A	Timer A4 mode register
0001A		00005A	Timer B0 mode register
0001D	Pulse output data register 1	00005C	Timer B1 mode register
0001D	Pulse output data register 0	00005D	Timer B2 mode register
0001E	A-D control register 0	00005E	Processor mode register 0
0001F	A-D control register 1	00005F	Processor mode register 1
00020	, and the second	000060	Watchdog timer register
00021	A-D register 0	000061	Watchdog timer frequency selection flag
00022	A-D register 1	000062	Waveform output mode register
00023	A-D register 1	000063	Reserved area (Note)
00024	A-D register 2	000064	UART2 transmit/receive mode register
00025	7 D Toglotor 2	000065	UART2 baud rate register (BRG2)
00026 00027	A-D register 3	000066 000067	UART2 transmission buffer register
00028	A-D register 4	000068	UART2 transmit/receive control register 0
00029	- 5	000069	UART2 transmit/receive control register 1
0002A	A-D register 5	00006A	UART2 receive buffer register
0002B		00006B	
0002C	A-D register 6	00006C	Oscillation circuit control register 0
0002D		00006D 00006E	Port function control register Serial transmit control register
0002E 0002F	A-D register 7	00006E	Oscillation circuit control register 1
0002F	UART 0 transmit/receive mode register	000070	A-D/UART2 trans./rece. interrupt control register
00030	UART 0 transmitreceive mode register UART 0 baud rate register (BRG0)	000070	UART 0 transmission interrupt control register
00031	,	000071	UART 0 receive interrupt control register
00032	UART 0 transmission buffer register	000072	UART 1 transmission interrupt control register
00034	UART 0 transmit/receive control register 0	000074	UART 1 receive interrupt control register
00035	UART 0 transmit/receive control register 1	000075	Timer A0 interrupt control register
00036	UART 0 receive buffer register	000076	Timer A1 interrupt control register
00037		000077	Timer A2 interrupt control register
00038	UART 1 transmit/receive mode register	000078	Timer A3 interrupt control register
00039	UART 1 baud rate register (BRG1)	000079	Timer A4 interrupt control register
0003A	UART 1 transmission buffer register	00007A	Timer B1 interrupt control register
0003B	, and the second	00007B	Timer B1 interrupt control register
0003C	UART 1 transmit/receive control register 0	00007C	Timer B2 interrupt control register
0003D 0003E	UART 1 transmit/receive control register 1	00007D	INTo interrupt control register
เทยเ≾๒	UART 1 receive buffer register	00007E	INT ₁ interrupt control register

Fig. 2 Location of internal peripheral devices and interrupt control registers





Pulse output port mode

The pulse motor drive waveform can be output by using plural internal timer A.

Figure 3 shows a block diagram for pulse output port mode. In the pulse output port mode, two pairs of four-bit pulse output ports are used. Whether using pulse output port or not can be selected by waveform output selection bit (bit 0, bit 1) of waveform output mode register (6216 address) shown in Figure 4. When bit 0 of waveform output selection bit is set to "1", RTP10, RTP11, RTP12, and RTP13 are used as pulse output ports, and when bit 1 of waveform output selection bit is set to "1", RTP00, RTP01, RTP02, and RTP03 are used as pulse output ports. When bits 1 and 0 of waveform output selection bit are set to "1", RTP10, RTP11, RTP12, and RTP13, and RTP00, RTP01, RTP02, and RTP03 are used as pulse output ports. The ports not used as pulse output ports can be used as normal parallel ports, timer input/output or key input interruput input.

In the pulse output port mode, set timers A0 and A2 to timer mode as timers A0 and A2 are used. Figure 5 shows the bit configuration of timer A0, A2 mode registers in pulse output port mode.

Data can be set in each bit of the pulse output data register corresponding to four ports selected as pulse output ports. Figure 6 shows the bit configuration of the pulse output data register. The contents of the pulse output data register 1 (low-order four bits of 1C16 address) corresponding to RTP10, RTP11, RTP12, and RTP13 is output to the ports each time the counter of timer A2 becomes 000016. The contents of the pulse output data register 0 (low-order four bits of 1D16 address) corresponding to RTP00, RTP01, RTP02, and RTP03 is output to the ports each time the counter of timer A0 becomes 000016.

Figure 7 shows example of waveforms in pulse output port mode. When "0" is written to a specified bit of the pulse output data register, "L" level is output to the corresponding pulse output port when the counter of corresponding timer becomes 000016, and when "1" is written, "H" level is output to the pulse output port.

Pulse width modulation can be applied to each pulse output port. Since pulse width modulation involves the use of timers A1 and A3, activate these timers in pulse width modulation mode.

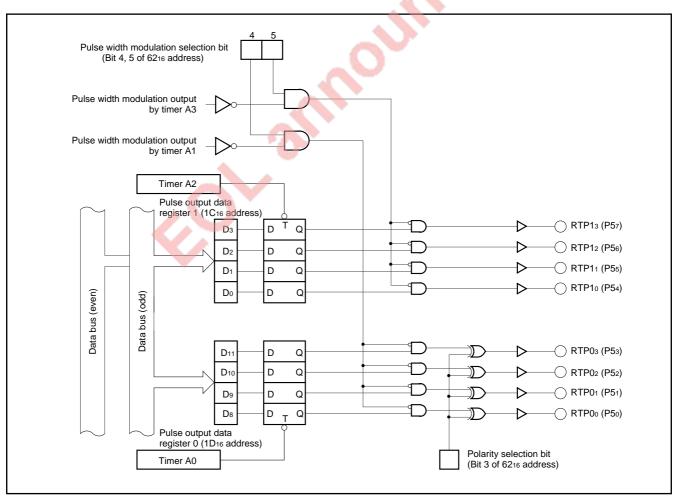


Fig. 3 Block diagram for pulse output port mode





RTP10, RTP11, RTP12, and RTP13 are applied pulse width modulation by timer A3 by setting the pulse width modulation selection bit by timer A3 (bit 5) of the waveform output mode register to "1".

RTP00, RTP01, RTP02, and RTP03 are applied pulse width modulation by timer A1 by setting the pulse width modulation selection bit by timer A1 (bit 4) of the waveform output mode register to "1".

The contents of the pulse output data register 0 can be reversed and output to pulse output ports RTP00, RTP01, RTP02, and RTP03 by the polarity selection bit (bit 3) of the waveform output mode register. When the polarity selection bit is "0", the contents of the pulse output data register 0 is output unchangeably, and when "1", the contents of the pulse output data register 0 is reversed and output. When pulse width modulation is applied, likewise the polarity reverse to pulse width modulation can be selected by the polarity selection bit.

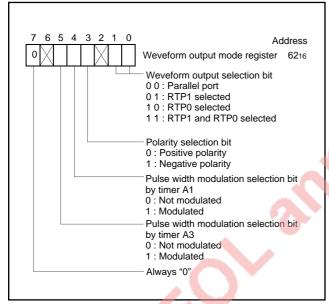


Fig. 4 Waveform output mode register bit configuration

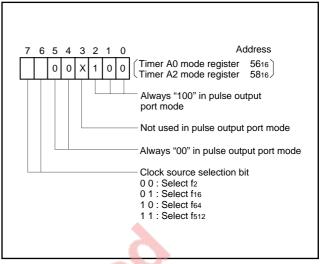


Fig. 5 Timer A0, A2 mode register bit configuration in pulse output port mode

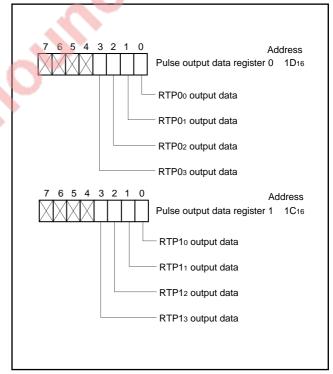


Fig. 6 Pulse output data register bit configuration



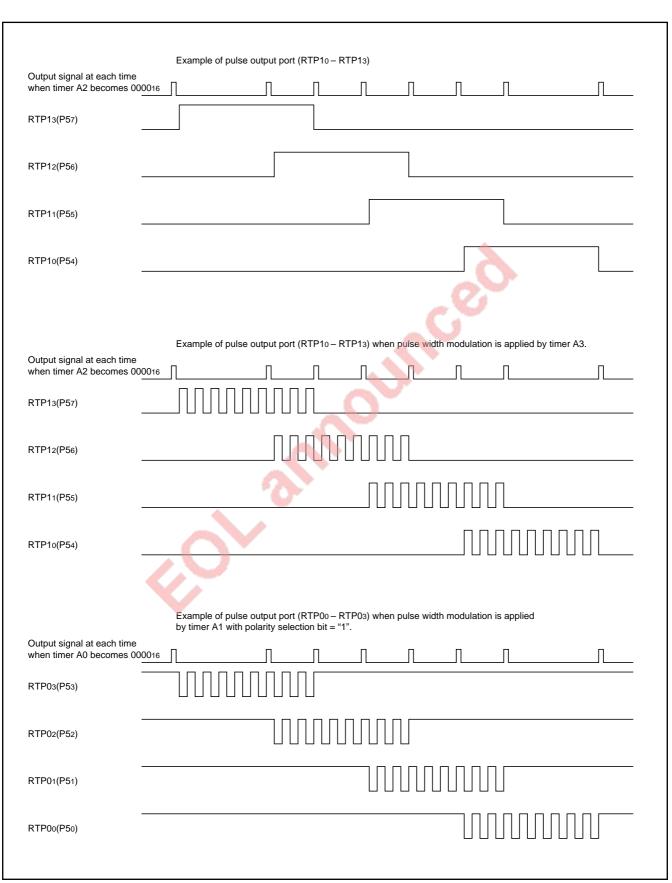


Fig. 7 Example of waveforms in pulse output port mode





16-BIT CMOS MICROCOMPUTER

PROCESSOR MODE

Only the microprocessor mode can be selected.

Figure 9 shows the functions of pins $P00/\overline{CS}_0 = P47$ in the microprocessor mode.

Figure 10 shows external memory area for the microprocessor mode. Access to the external memory is affected by the BYTE pin, the wait bit (bit 2 of the processor mode register 0 at address $5E_{16}$), and the wait selection bit (bit 0 of the processor mode register 1 at address $5F_{16}$).

• BYTE pin

When accessing the external memory, the level of the BYTE pin is used to determine whether to use the data bus as 8-bit width or 16-bit width.

The data bus has a width of 8 bits when level of the BYTE pin is "H", and pins P20/A0/D0 - P27/A7/D7 are the data I/O pins.

The data bus has a width of 16 bits when the level of the BYTE pin is "L", and pins P2o/Ao/Do — P27/A7/D7 and pins P1o/A8/D8 — P17/A15/D15 are the data I/O pins.

When accessing the internal memory, the data bus always has a width of 16 bits regardless of the BYTE pin level.

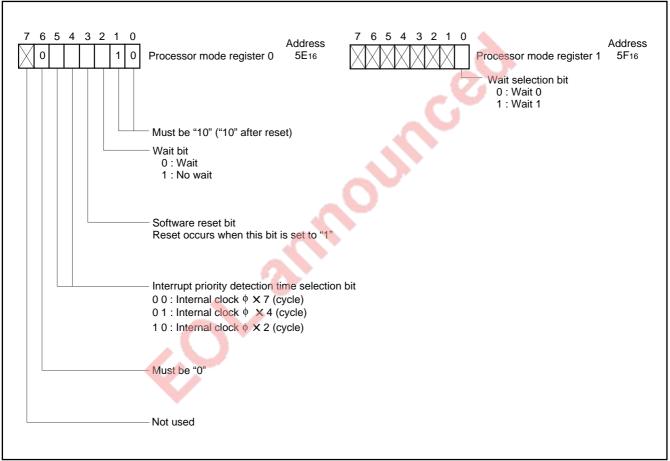


Fig. 8 Processor mode register bit configuration

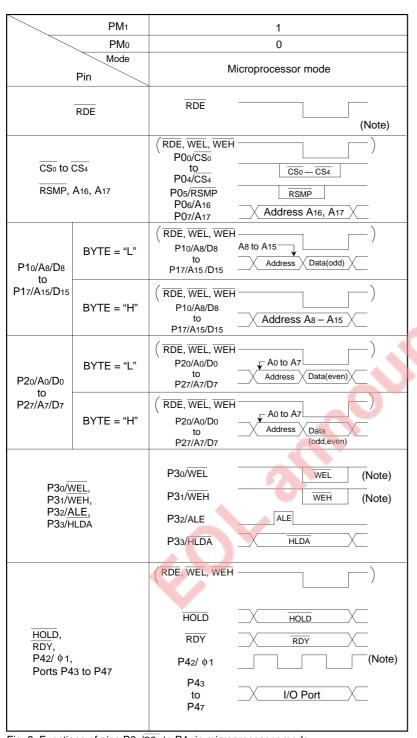


Fig. 9 Functions of pins $P00/\overline{CS_0}$ to P47 in microprocessor mode

Note. The signal output disable selection bit (bit 6 of the oscillation circuit control register 0) can stop the φ 1 output in the microprocessor mode. In this mode, signals RDE, WEL, WEH can also be fixed to "H" when the internal memory area is accessed.





16-BIT CMOS MICROCOMPUTER

• Wait bit

As shown in Figure 11, when the external memory area is accessed with the wait bit (bit 2 of the processor mode register 0 at address 5E₁₆) cleared to "0", the access time can be extended compared with no wait (the wait bit is "1").

The access time is extended in two ways and this is selected with the wait selection bit (bit 0 of the processor mode register 1 at address 5F₁₆).

When this bit is "1", the access time is 1.5 times compared to that for no wait. When this bit is "0", the access time is twice compared to that for no wait.

At reset, the wait bit and the wait selection bit are "0".

Access to internal memory area is always performed in the no wait mode regardless of the wait bit.

The processor modes are described below.

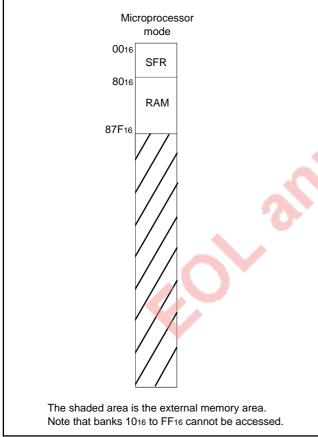


Fig. 10 External memory area for microprocessor mode

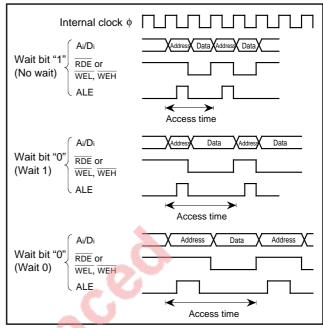


Fig. 11 Relationship between wait bit, wait selection bit, and access time

(1) Microprocessor mode [10]

The microcomputer enters the microprocessor mode after connecting the CNVss pin to Vcc and starting from reset.

Pin $\overline{\text{RDE}}$ is the output pin for the read enable signal ($\overline{\text{RDE}}$).

 $\overline{\text{RDE}}$ is "L" during the data read term in the read cycle. When the internal memory area is read, $\overline{\text{RDE}}$ can be fixed to "H" by setting the signal output disabe selection bit (bit 6 of the oscillation circuit control register 0) to "1".



16-BIT CMOS MICROCOMPUTER

 $\overline{\text{CS}_0}$ to $\overline{\text{CS}_4}$ are the chip select signals and are "L" when the address shown in Table 2 is accessed. $\overline{\text{RSMP}}$ is the ready-sampling signal which is output for the $\overline{\text{RDY}}$ input described later when the external memory area is accessed. By inputting logical AND of $\overline{\text{RSMP}}$ and $\overline{\text{CS}_0}$ (n = 0 to 4) to the $\overline{\text{RDY}}$ pin, read/write term for any address areas can be extended by 1 cycle of clock ϕ 1. In addition, the read/write term can also be extended by 2 cycles of clock ϕ 1 if the above function and wait 0/1 function specified with the wait bit are used together.

Pins P10/A8/D8 - P17/A15/D15 have two functions depending on the level of the BYTE pin.

When the BYTE pin level is "L", pins P1o/A8/D8 — P1 π /A15/D15 function as address (A8 to A15) output pins while \overline{RDE} or \overline{WEL} , \overline{WEH} are "H" and as odd address data I/O pins while these signals are "L". However, if an internal memory is read, external data is ignored while \overline{RDE} is "I".

When the BYTE pin level is "H", pins P1o/A8/D8 — P1 τ /A15/D15 function as address (A8 to A15) output pins.

Pins P20/A0/D0 - P27/A7/D7 have two functions depending on the level of the BYTE pin.

When the BYTE pin level is "L", pins P2o/Ao/Do — P27/A7/D7 function as address (Ao to A7) output pins while $\overline{\text{RDE}}$ or $\overline{\text{WEL}}$, $\overline{\text{WEH}}$ are "H" and as even address data I/O pins while these signals are "L". However, if an internal memory is read, external data is ignored while $\overline{\text{RDE}}$ is "L".

When the BYTE pin level is "H", pins P2o/Ao/Do - P27/A7/D7 function as address (Ao to A7) output pins while \overline{RDE} or \overline{WEL} , \overline{WEH} are "H" and as even and odd address data I/O pins while these signals are "L". However, if an internal memory is read, external data is ignored while \overline{RDE} is "L".

WEL, WEH are the write-enable low signal and the write-enable high signal, respectively. These signals are "L" during the data write term of the write cycle, but their operations differ depending on the BYTE pin level.

In the case the BYTE pin level is "L", WEL is "L" when writing to an even address, WEH is "L" when writing to an odd address, and both WEL and WEH are "L" when writing to even and odd addresses. In the case the BYTE pin level is "H", regardless of address, only WEL is "L", and WEH retains "H". WEL and WEH can also be fixed to "H" when the internal memory is accessed, same as RDE, by writing "1" to the signal output disable selection bit.

ALE is an address latch enable signal used to latch the address signal from a multiplexed signal of address and data. The latch is transparent while ALE is "H" to let the address signal pass through and held while ALE is "L".

HLDA is a hold acknowledge signal and is used to notify externally when the microcomputer receives HOLD input and enters into hold state.

 $\overline{\text{HOLD}}$ is a hold request signal. It is an input signal used to put the microcomputer in hold state. $\overline{\text{HOLD}}$ input is accepted when the internal clock ϕ falls from "H" level to "L" level while the bus is not used.

Pins $P00/\overline{CS_0}$ — $P31/\overline{WEH}$ and \overline{RDE} are floating while the microcomputer stays in hold state. After \overline{HLDA} signal changes to "L" level and one cycle of internal clock ϕ passed, these ports become floating. After \overline{HLDA} signal changes to "H" level and one cycle of internal clock ϕ passed, these ports are released from floating state.

 \overline{RDY} is a ready signal. If this signal goes "L", the internal clock ϕ stops at "L". \overline{RDY} is used when slow external memory is attached. P42/ ϕ 1 pin is an output pin for clock ϕ 1. The ϕ 1 output is independent of \overline{RDY} and does not stop even when internal clock ϕ stops because of "L" input to the \overline{RDY} pin.

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16-BIT CMOS MICROCOMPUTER

As shown in Table 3, $\,\phi\,$ 1 output can be stopped with the signal output disable selection bit = "1". In this case, write "1" to the port P42 direction register.

Table 1 shows the relationship between the CNVss pin input level and the processor mode.

Table 1. Relationship between CNVss pin input levels and processor mode

CNVss	Mode	Description
Vcc		Microprocessor mode upon starting after reset.

Table 2. Relationship between access addresses and chip-select signals CSo to CS4

Chip-select	Area	Access address		
signal	Alea	Microprocessor mode		
	The first half of bank 0016 except	00 088016		
CS ₀	internal memory area	to		
	internal memory area	00 7FFF ₁₆		
	The latter half of bank 0016 except	00 800016		
CS ₁	internal memory area and banks	to		
	0116 to 0316.	03 FFFF16		
		04 000016		
CS ₂	Banks 0416 to 0716	to		
		07 FFFF16		
		08 000016		
CS ₃	Banks 0816 to 0B16	to		
		0B FFFF16		
		OC 000016		
CS ₄	Banks 0C ₁₆ to 0F ₁₆	to		
		OF FFFF16		

Table 3. Function of signal output disable selection bit CM₆ (bit 6 of oscillation circuit control register 0)

Processor mode	Pin	Function			
Frocessor mode	FIII	CM6 = "0"	CM6 = "1"		
Microprocessor mode	RDE, WEL, WEH	RDE, WEL, WEH are output when the internal/external memory area is accessed.	RDE, WEL, WEH are output only when the external memory area is accessed.		
	RDE	After WIT/STP instruction is executed, "H" is output.	"L" is output after WIT/STP instruction is executed * Standby state selection bit (bit 0 of port function control register) must be set to "1".		
	ф 1	Clock ϕ 1 is output independent of ϕ 1 output selection bit.	"H" or "L" is output. (Contents of P42 port latch is output.) * Port P42 direction register must be set to "1".		

Note. Functions shown in Table 3 cannot be emulated with a debugger. For the oscillation circuit control register 0 and port function control register, refer to Figures 64 and 11 in data sheet "M37735MHBXXXFP", respectively.





16-BIT CMOS MICROCOMPUTER

RESET CIRCUIT

The microcomputer is released from the reset state when the $\overline{\text{RESET}}$ pin is returned to "H" level after holding it at "L" level with the power source voltage at 5 V \pm 10%. Program execution starts at the address formed by setting address A23 – A16 to 0016, A15 – A8 to the contents of address FFFF16, and A7 – A0 to the contents of address FFFE16. Figure 13 shows an example of a reset circuit. If the stabilized clock is input from the external to the main-clock oscillation circuit, the reset

input voltage must be 0.9 V or less when the power source voltage reaches 4.5 V. If a resonator/oscillator is connected to the main-clock oscillation circuit, change the reset input voltage from "L" to "H" after the main-clock oscillation is fully stabilized.

Figure 12 shows the status of the internal registers during reset.

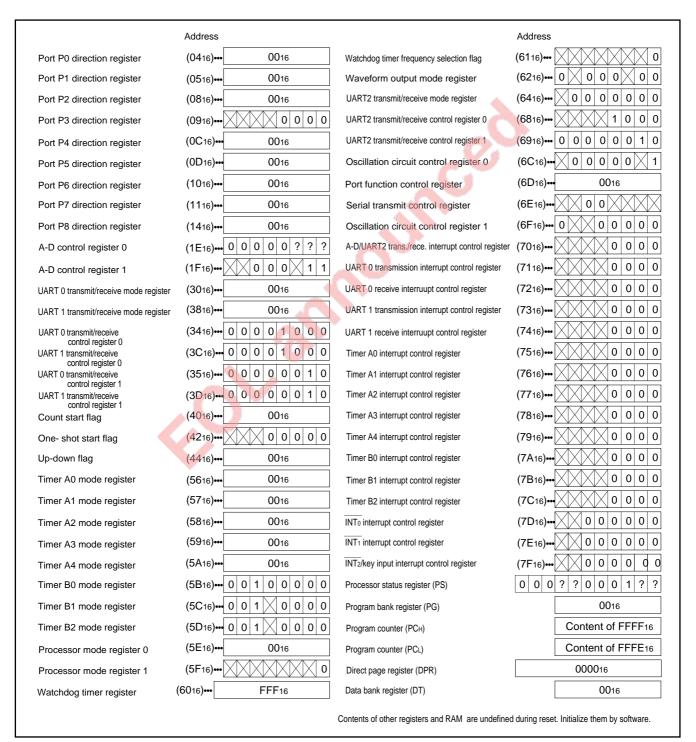


Fig. 12 Microcomputer internal status during reset







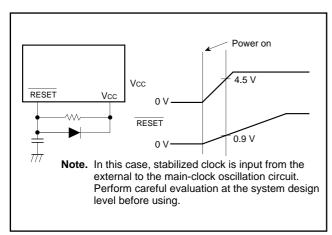


Fig. 13 Example of a reset circuit

ADDRESSING MODES

The M37735S4BFP has 28 powerful addressing modes. Refer to the MITSUBISHI SEMICONDUCTORS DATA BOOK SINGLE-CHIP 16-BIT MICROCOMPUTERS for the details of each addressing mode.

MACHINE INSTRUCTION LIST

The M37735S4BFP has 103 machine instructions. Refer to the MITSUBISHI SEMICONDUCTORS DATA BOOK SINGLE-CHIP 16-BIT MICROCOMPUTERS for details.





16-BIT CMOS MICROCOMPUTER

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Unit
Vcc	Power source voltage		−0.3 to +7	V
AVcc	Analog power source voltage		-0.3 to +7	V
Vı	Input voltage RESET, CNVss, BYTE		-0.3 to +12	V
Vı	Input voltage P10/A8/D8 – P17/A15/D15, P20/A0/D0 – P27/A7/D7, P43 – P47, P50 – P57, P60 – P67, P70 – P77, P80 – P87, VREF, XIN, HOLD, RDY		-0.3 to Vcc + 0.3	V
Vo	Output voltage $P00/\overline{CS0} = P07/A17$, $P10/A8/D8 = P17/A15/D15$, $P20/A0/D0 = P27/A7/D7$, $P30/\overline{WEL} = P33/\overline{HLDA}$, $P42/$ ϕ 1, $P43 = P47$, $P50 = P57$, $P60 = P67$, $P70 = P77$, $P80 = P87$, $Xout$, \overline{RDE}		-0.3 to Vcc + 0.3	V
Pd	Power dissipation	Ta = 25 °C	300	mW
Topr	Operating temperature		-20 to +85	°C
Tstg	Storage temperature		-40 to +150	°C

RECOMMENDED OPERATING CONDITIONS (Vcc = 5 V ± 10%, Ta = -20 to +85 °C, unless otherwise noted)

0 1 1	P	ON THE PARTY	Limits		J
Symbol	Parameter		Тур.	Max.	Unit
\	f(XIN): Operating	4.5	5.0	5.5	V
Vcc	Power source voltage $f(XiN)$: Stopped, $f(XciN) = 32.768 \text{ kHz}$	2.7		5.5	V
AVcc	Analog power source voltage		Vcc		V
Vss	Power source voltage		0		V
AVss	Analog power source voltage		0		V
VIH	High-level input voltage HOLD, RDY, P43 – P47, P50 – P57, P60 – P67, P70 – P77, P80 – P87, XIN, RESET, CNVss, BYTE, XCIN (Note 3)	0.8 Vcc		Vcc	V
VIH	High-level input voltage P10/A8/D8 – P17/A15/D15, P20/A0/D0 – P27/A7/D7	0.5 Vcc		Vcc	V
VIL	Low-level input voltage HOLD, RDY, P43 – P47, P50 – P57, P60 – P67, P70 – P77, P80 – P87, XIN, RESET, CNVss, BYTE, XCIN (Note 3)	0		0.2Vcc	V
VIL	Low-level input voltage P1o/As/Ds – P17/A15/D15, P2o/Ao/Do – P27/A7/D7	0		0.16Vcc	V
IOH(peak)	High-level peak output current P00/CS ₀ – P07/A17, P10/A8/D8 – P17/A15/D15, P20/A0/D0 – P27/A7/D7, P30/WEL – P33/HLDA, P42/ φ 1, P43 – P47, P50 – P57, P60 – P67, P70 – P77, P80 – P87			-10	mA
IOH(avg)	High-level average output current P0o/CSo = P07/A17, P1o/A8/D8 = P17/A15/D15, P2o/A0/D0 = P27/A7/D7, P3o/WEL = P33/HLDA, P42/ \$\phi\$ 1, P43 = P47, P50 = P57, P60 = P67, P70 = P77, P80 = P87			-5	mA
IOL(peak)	Low-level peak output current P0o/CS ₀ – P07/A17, P1o/A8/D8 – P17/A15/D15, P2o/Ao/D0 – P27/A7/D7, P3o/WEL – P33/HLDA, P42/ φ 1, P43, P54 – P57, P60 – P67, P70 – P77, P80 – P87			10	mA
IOL(peak)	Low-level peak output current P44 – P47, P50 – P53			20	mA
lOL(avg)	Low-level average output current P0o/CSo - P07/A17, P1o/A8/D8 - P17/A15/D15, P2o/Ao/D0 - P27/A7/D7, P3o/WEL - P33/HLDA, P42/ \$\phi\$ 1, P43, P54 - P57, P60 - P67, P70 - P77, P80 - P87			5	mA
IOL(avg)	Low-level average output current P44 – P47, P50 – P53			15	mA
f(XIN)	Main-clock oscillation frequency (Note 4)			25	MHz
f(Xcin)	Sub-clock oscillation frequency		32.768	50	kHz

Notes 1. Average output current is the average value of a 100 ms interval.

- 2. The sum of IoL(peak) for ports P0v/CSo P07/A17, P1v/A8/D8 P17/A15/D15, P2v/Av/D7, P3v/WEL P33/HLDA and P8 must be 80 mA or less, the sum of IoH(peak) for ports P0v/CSo P07/A17, P1v/A8/D8 P17/A15/D15, P2v/Av/D0 P27/A7/D7, P3v/WEL P33/HLDA and P8 must be 80 mA or less, the sum of IoH(peak) for ports P4, P5, P6, and P7 must be 100 mA or less, and the sum of IoH(peak) for ports P4, P5, P6, and P7 must be 80 mA or less.
- 3. Limits VIH and VIL for XCIN are applied when the sub clock external input selection bit = "1".
- **4.** The maximum value of $f(X_{IN}) = 12.5$ MHz when the main clock division selection bit = "1".







ELECTRICAL CHARACTERISTICS (Vcc = 5 V, Vss = 0 V, Ta = -20 to +85 °C, f(XIN) = 25 MHz, unless otherwise noted)

High-level output voltage P0o/CSo - P07/A17, P1o/As/Ds - P17/A15/D15, P2o/Ac/Do - P27/A7/D7, P33/HLDA, P4z/ φ 1, P43 - P47, P5o - P57, P6o - P67, P7o - P77, P8o - P87 Ioh = -10 mA 3 V V V V V V V V V	0	Description	Tankana Pilana		Limits		
VOH P2/JA/DD - P2/JA/DD, P3/HDA, P4/9 1, P43 - P47, P50 - P57, P60 - P67, P70 - P77, P80 - P87, P80 - P	Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
Voh High-level output voltage P0xCSs - P0x/Axt, P1x/Ax0Ds - P1x/AxxD1s, P2xAx0Dr - P2x/AxvDr, P3xyHDA, P4z φ 1 In H = -400 μA 4.7 V V V V High-level output voltage P3xyWEL, P3xyHDA, P4z φ 1 In H = -400 μA 4.8 V V V V V High-level output voltage RDE In High-level output voltage RDE In High-level output voltage RDE In High-level output voltage P0x(CSs - P0x/Axt, P1x/Ax0Ds - P1x/Ax0Ds, P2x/Ax0Dr - P2x/Ax0Dr - P2x/Ax0Dr, P3xyHDA, P4z φ 1 In H = -400 μA 4.8 V V V V V V V V V	Vон	P2 ₀ /A ₀ /D ₀ – P2 ₇ /A ₇ /D ₇ , P3 ₃ /HLDA, P4 ₂ / ϕ 1, P4 ₃ – P4 ₇ , P5 ₀ – P5 ₇ , P6 ₀ – P6 ₇ , P7 ₀ – P7 ₇ ,	Iон = -10 mA	3			V
Voh High-level output voltage P3.0/VEL, P31/WEH, P32/ALE IoH = -400 μ A 4.8 Voh = -400 μ A 4.8 Voh = -400 μ A A.8 Voh = -400 μ A Voh = -400 μ A A.8 Voh = -400 μ A A.8	Vон	High-level output voltage P00/CS0 – P07/A17, P10/A8/D8 – P17/A15/D15,	loн = -400 μA	4.7			V
Note Night-level output voltage P0s/CSs - P07/A17, P1s/As/DE-P17/A15/DIS, P2s/Av/Do - P27/A7/D7, P3s/HLDA, P4z/ φ 1, P43, P54 - P57, P6o - P67, P7o - P77, P8o - P87 Vol. Low-level output voltage P0s/CSs - P07/A17, P1s/As/Ds - P17/A15/D15, P2s/Av/Do - P27/A7/D7, P3s/HLDA, P4z/ φ 1 loL = 20 mA 2 V Vol. Low-level output voltage P0s/CSs - P07/A17, P1s/As/Ds - P17/A15/D15, P2s/Av/Do - P27/A7/D7, P3s/HLDA, P4z/ φ 1 loL = 20 mA 0.45 V Vol. Low-level output voltage P0s/CSs - P07/A17, P1s/As/Ds - P17/A15/D15, P2s/Av/Do - P27/A7/D7, P3s/HLDA, P4z/ φ 1 loL = 2 mA 0.45 V Vol. Low-level output voltage RDE loL = 20 mA 0.45 V Vol. Low-level output voltage RDE loL = 20 mA 0.43 V Vol. Low-level output voltage RDE loL = 20 mA 0.43 V Vol. Low-level output voltage RDE loL = 20 mA 0.43 V Vol. Low-level output voltage RDE loL = 20 mA 0.43 V Vol. Low-level output voltage RDE loL = 20 mA 0.43 V Vol. Low-level output voltage RDE loL = 20 mA 0.43 V Vol. Low-level output voltage RDE loL = 20 mA 0.44 V Vol. University Average RDE loL = 20 mA 0.43 V Vol. Low-level output voltage RDE loL = 20 mA 0.44 V Vol. University Average RDE loL = 20 mA 0.44 V Vol. University Average RDE loL = 20 mA 0.44 V Vol. University Average RDE loL = 20 mA 0.44 V Vol. University Average RDE lol = 20 mA 0.44 V Vol. University Average RDE lol = 20 mA 0.44 V Vol. University Average RDE lol = 20 mA 0.45 V Vol. University Average RDE lol = 20 mA 0.44 V Vol. University Average RDE lol = 20 mA 0.44 V Vol. University Average RDE lol = 20 mA 0.44 V Vol. University Average RDE lol = 20 mA 0.44 V Vol. University Average RDE lol = 20 mA 0.44 V Vol. University Average RDE lol = 20 mA 0.44 V Vol. University Average RDE lol = 20 mA 0.44 V Vol. University Average	Vон	High-level output voltage P30/WEL, P31/WEH, P32/ALE					V
Low-level output voltage P0a/CS ₂ - P07/A17, P1a/As/Ds - P17/A15/D15, P2a/Aa/Ds - P27/A7/Dr, P3s/HIDA, P4a/ 9 1, P4s, P5a - P5r, P6a - P6r, P7a - P7r, P8a - P8r 7 80 - P6r, P7a - P7r, P8a - P8r 7 80 - P6r, P7a - P7r, P8a - P8r 7 80 - P6r, P7a - P7r, P8a - P8r 7 80 - P6r, P7a - P7r, P8a - P8r 7 80 - P6r, P7a - P7r, P8a - P8r 7 80 - P6r, P7a - P7r, P8a - P8r 7 80 - P6r, P7a - P7r, P8a - P8r 7 80 - P6r, P7a - P7r, P8a - P8r, P6a - P6r, P7a - P7r, P8a - P8r, Na, RESET, CNVss, BYTE	Vон	High-level output voltage RDE					V
Vol	VoL	P20/A0/D0 – P27/A7/D7, P33/HLDA, P42/ φ 1, P43, P54 – P57, P60 – P67, P70 – P77,				2	V
Vol. Low-level output voltage P30/WEL, P31/WEH, P32/ALE IoL = 10 mA IoL = 2 mA IoL = 2 mA IoL = 2 mA IoL = 10 mA IoL = 2 mA IoL =	VoL	Low-level output voltage P44 - P47, P50 - P53	loL = 20 mA	Sand .		2	V
Vol. Low-level output voltage P3o/WEL, P31/WEH, P32/ALE IoL = 2 mA	VoL	, ,	loL = 2 mA	3		0.45	V
IoL = 2 mA 0.43 0.43 1.6 V V V V V V V V V	Voi	Low-level output voltage P30/WEL P31/WEH P32/ALE	loL = 10 mA			1.9	\/
Vol. Low-level output voltage RDE IoL = 2 mA IoL		Low lovel output voltago i outreet, i outreet, i outreet	IoL = 2 mA			0.43	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
Hysteresis HOLD, RDY, TAOIN - TA4IN, TBOIN - TB2IN, INTo - INT	Vol	Low-level output voltage RDE					V
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$, ·	loL = 2 mA			0.4	
VT+ - VT-	VT+ - VT-	INTo - INT2, ADTRG, CTS0, CTS1, CTS2, CLK0,		0.4		1	V
VT+ - VT- Hysteresis XCIN (When external clock is input) 0.1 0.4 V High-level input current P10/As/Ds - P17/Ats/D15, P20/Ao/Do - P27/A7/D7, P43 - P47, VI = 5 V 5 μ A IIII Low-level input current P10/As/Ds - P17/Ats/D15, VI = 5 V 5 μ A IIIL Low-level input current P10/As/Ds - P17/Ats/D15, VI = 0 V -5 μ A IIIL P50 - P53, P60, P61, P65 - P67, P70 - P77, VI = 0 V -5 μ A IIIL Low-level input current P54 - P57, P62 - P64 VI = 0 V, without a pull-up transistor -5 μ A	VT+ - VT-	Hysteresis RESET		0.2		0.5	V
High-level input current P1o/As/Ds - P1r/A1s/D15, P2o/Ao/Do - P2r/Ar/D7, P43 - P47, P50 - P57, P60 - P67, P70 - P77, P80 - P87, XIN, RESET, CNVss, BYTE Low-level input current P1o/As/Ds - P1r/A1s/D15, P2o/Ao/Do - P2r/Ar/D7, P43 - P47, P50 - P53, P60, P61, P65 - P67, P70 - P77, P80 - P87, XIN, RESET, CNVss, BYTE VI = 0 V -5	VT+ - VT-	Hysteresis XIN	Table 1	0.1		0.4	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	VT+ - VT-	Hysteresis Xcın (When external clock is input)		0.1		0.4	V
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	lін	P20/A0/D0 – P27/A7/D7, P43 – P47, P50 – P57, P60 – P67, P70 – P77,	VI = 5 V			5	μА
$\begin{tabular}{ l l l l l l l l l l l l l l l l l l l$	lı∟	P20/A0/D0 - P27/A7/D7, P43 - P47, P50 - P53, P60, P61, P65 - P67, P70 - P77,	VI = 0 V			-5	μΑ
V _I = 0 V, with a pull-up	lı.	2,0	without a pull-up transistor			-5	μА
		22.0.2.2.2.2.2.2.2.2.2.2.2.2.2.2.2.2.2.	with a pull-up	-0.25	-0.5	-1.0	mA
	VRAM	RAM hold voltage		2			V





ELECTRICAL CHARACTERISTICS (Vcc = 5 V, Vss = 0 V, Ta = -20 to +85 °C, unless otherwise noted)

Symbol	Parameter		Test conditions		Limits	Max.	Unit
			Vcc = 5 V, f(X _I N) = 25 MHz (square waveform), (f(f ₂) = 12.5 MHz), f(X _C IN) = 32.768 kHz, in operating (Note 1)	Min.	Тур. 11.4	22.8	mA
			Vcc = 5 V, f(XIN) = 25 MHz (square waveform), (f(f2) = 1.5625 MHz), f(XCIN): Stopped in operating (Note 1)		1.6	3.2	mA
Icc	Power source current	When external bus is in use, output pins are open, and other pins are Vss.	Vcc = 5 V, f(XIN) = 25 MHz (square waveform), f(XCIN) = 32.768 kHz, when a WIT instruction is executed (Note 2)		10	20	μА
			Vcc = 5 V, f(XIN): Stopped, f(XCIN) = 32.768 kHz, in operating (Note 3)	05	60	120	μА
			Vcc = 5 V, f(XIN): Stopped, f(XCIN) = 32.768 kHz, when a WIT instruction is executed (Note 4)		5	10	μА
			Ta = 25 °C, when clock is stopped			1	μΑ
			Ta = 85 °C, when clock is stopped			20	μΑ

- **Notes 1.** This applies when the main clock external input selection bit = "1", the main clock division selection bit = "0", and the signal output stop bit = "1".
 - 2. This applies when the main clock external input selection bit = "1" and the system clock stop bit at wait state = "1".
 - 3. This applies when CPU and the clock timer are operating with the sub clock (32.768 kHz) selected as the system clock.
 - 4. This applies when the Xcout drivability selection bit = "0" and the system clock stop bit at wait state = "1".

A-D CONVERTER CHARACTERISTICS

 $(Vcc = AVcc = 5 \text{ V}, Vss = AVss = 0 \text{ V}, Ta = -20 \text{ to } +85 \text{ °C}, f(XIN) = 25 \text{ MHz}, unless otherwise noted (Note))}$

Symbol	Parameter	Test conditions		Limits		11-2
	1 diameter	rest conditions	Min.	Тур.	Max.	Unit
_	Resolution	VREF = VCC			10	Bits
_	Absolute accuracy	VREF = VCC			± 3	LSB
RLADDER	Ladder resistance	VREF = VCC	10		25	kΩ
tCONV	Conversion time		9.44			μs
VREF	Reference voltage		2		Vcc	V
VIA	Analog input voltage		0		Vref	V

Note. This applies when the main clock division selection bit = "0" and f(f2) = 12.5 MHz.





 $\textbf{TIMING REQUIREMENTS} \text{ (Vcc = 5 V $\pm $ 10\%, Vss = 0 V, Ta = -20 to +85 °C, f(XIN) = 25 MHz, unless otherwise noted (Note 1)) }$

Notes 1. This applies when the main clock division selection bit = "0" and f(f2) = 12.5 MHz.

2. Input signal's rise/fall time must be 100 ns or less, unless otherwise noted.

External clock input

Symbol	Parameter	Limits		Unit
	i diamotoi	Min.	Max.	Unit
tc	External clock input cycle time (Note 1)	40		ns
tw(H)	External clock input high-level pulse width (Note 2)	15		ns
tw(L)	External clock input low-level pulse width (Note 2)	15		ns
tr	External clock rise time		8	ns
tr	External clock fall time		8	ns

Notes 1. When the main clock division selection bit = "1", the minimum value of tc = 80 ns.

2. When the main clock division selection bit = "1", values of $t_{W(H)}/t_{c}$ and $t_{W(L)}/t_{c}$ must be set to values from 0.45 through 0.55.

Microprocessor mode

Symbol	Parameter	Limits		Unit
Symbol	i arameter	Min.	Max.	
tsu(P4D-RDE)	Port P4 input setup time	60		ns
tsu(P5D-RDE)	Port P5 input setup time	60		ns
tsu(P6D-RDE)	Port P6 input setup time	60		ns
tsu(P7D-RDE)	Port P7 input setup time	60		ns
tsu(P8D-RDE)	Port P8 input setup time	60		ns
th(RDE-P4D)	Port P4 input hold time	0		ns
th(RDE-P5D)	Port P5 input hold time	0		ns
th(RDE-P6D)	Port P6 input hold time	0		ns
th(RDE-P7D)	Port P7 input hold time	0		ns
th(RDE-P8D)	Port P8 input hold time	0		ns

Microprocessor mode

Symbol	Parameter	Limits	Unit	
	1 didinotor	Min.	Max.	Offic
tsu(D-RDE)	Data input setup time	32		ns
tsu(RDY- ϕ 1)	RDY input setup time	55		ns
tsu(HOLD- ϕ 1)	HOLD input setup time	55		ns
th(RDE-D)	Data input hold time	0		ns
th(\$ 1-RDY)	RDY input hold time	0		ns
th(ϕ 1–HOLD)	HOLD input hold time	0		ns





Timer A input (Count input in event counter mode)

Symbol	Parameter	Limits		Unit
	i didifficio	Min. Max.	Offic	
tc(TA)	TAin input cycle time	80		ns
tw(TAH)	TAil input high-level pulse width	40		ns
tw(TAL)	TAil input low-level pulse width	40		ns

Timer A input (Gating input in timer mode)

Symbol	Parameter	Limits		Unit
	i didifficio	Min.	Min. Max.	Ullit
tc(TA)	TAilN input cycle time (Note)	320		ns
tw(TAH)	TAiın input high-level pulse width (Note)	160		ns
tw(TAL)	TAin input low-level pulse width (Note)	160		ns

Note. Limits change depending on f(XIN). Refer to "DATA FORMULAS".

Timer A input (External trigger input in one-shot pulse mode)

Symbol	Parameter	L	imits	Unit
	i arameter	Min.	Max.	Ullit
tc(TA)	TAil input cycle time (Note)	320		ns
tw(TAH)	TAil input high-level pulse width	80		ns
tw(TAL)	TAil input low-level pulse width	80		ns

Note. Limits change depending on f(XIN). Refer to "DATA FORMULAS".

Timer A input (External trigger input in pulse width modulation mode)

Symbol	Parameter	Limits	Unit
Oyinboi	1 drameter	Min. Max.	Offic
tw(TAH)	TAiเพ input high-level pulse width	80	ns
tw(TAL)	TAin input low-level pulse width	80	ns

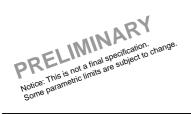
Timer A input (Up-down input in event counter mode)

Symbol	Parameter	Limits Min. Max.	nits	Unit
	i diamotor		Offic	
tc(UP)	TAiout input cycle time	2000		ns
tw(UPH)	TAiout input high-level pulse width	1000		ns
tw(UPL)	TAiout input low-level pulse width	1000		ns
tsu(UP-TiN)	TAiout input setup time	400		ns
th(TIN-UP)	TAiout input hold time	400		ns

Timer A input (Two-phase pulse input in event counter mode)

Symbol	Parameter	Lir	nits	Unit
	i didilicici	Min. Max.	OTIN	
tc(TA)	TAjın input cycle time	800		ns
tsu(TAjın-TAjout)	TAjın input setup time	200		ns
tsu(TAjout-TAjin)	TAjo∪⊤ input setup time	200		ns





Timer B input (Count input in event counter mode)

Symbol	Parameter	Lir	Limits	
Symbol	i didilicici	Min.	Max.	Unit
tc(TB)	TBiin input cycle time (one edge count)	80		ns
tw(TBH)	TBiin input high-level pulse width (one edge count)	40		ns
tw(TBL)	TBin input low-level pulse width (one edge count)	40		ns
tc(TB)	TBiin input cycle time (both edges count)	160		ns
tw(TBH)	TBiin input high-level pulse width (both edges count)	80		ns
tw(TBL)	TBiin input low-level pulse width (both edges count)	80		ns

Timer B input (Pulse period measurement mode)

Symbol	Parameter	Limits		Unit
	i arameter	Min.	Max.	Offic
tc(TB)	TBin input cycle time (Note)	320		ns
tw(TBH)	TBin input high-level pulse width (Note)	160		ns
tw(TBL)	TBiin input low-level pulse width (Note)	160		ns

Note. Limits change depending on f(XIN). Refer to "DATA FORMULAS".

Timer B input (Pulse width measurement mode)

Symbol	Parameter		mb.	Limits		Unit
			Contract of the Contract of th	Min.	Max.	Offic
tc(TB)	TBil input cycle time (Note)		•	320		ns
tw(TBH)	TBiin input high-level pulse width (Note)	6		160		ns
tw(TBL)	TBiin input low-level pulse width (Note)			160		ns

Note. Limits change depending on f(XIN). Refer to "DATA FORMULAS".

A-D trigger input

Symbol	Parameter		Limits		
Cymbol	1 didilictor	Min.	Max.	Unit	
tc(AD)	ADTRG input cycle time (minimum allowable trigger)	1000		ns	
tw(ADL)	ADTRG input low-level pulse width	125		ns	

Serial I/O

Symbol	Parameter	Lir	Unit	
Symbol	i arameter	Min.	Max.	Offic
tc(CK)	CLKi input cycle time	200		ns
tw(CKH)	CLKi input high-level pulse width	100		ns
tw(CKL)	CLKi input low-level pulse width	100		ns
td(C-Q)	TxDi output delay time		80	ns
th(C-Q)	TxDi hold time	0		ns
tsu(D-C)	RxDi input setup time	30		ns
th(C-D)	RxDi input hold time	90		ns

External interrupt INTi input, key input interrupt Kli input

Symbol	Parameter		Limits		
Syllibol	Faranteter	Min.	Max.	Unit	
tw(INH)	INTi input high-level pulse width	250		ns	
tw(INL)	INTi input low-level pulse width	250		ns	
tw(KIL)	Kli input low-level pulse width	250		ns	





DATA FORMULAS

Timer A input (Gating input in timer mode)

Symbol	Parameter	Limits		11-2
Symbol	i arameter	Min.	Max.	Unit
tc(TA)	TAil input cycle time	8 X 10° 2 • f(f2)		ns
tw(TAH)	TAiın input high-level pulse width	$\frac{4 \times 10^9}{2 \cdot f(f_2)}$		ns
tw(TAL)	TAiın input low-level pulse width	4 × 10 ⁹ 2 • f(f2)		ns

Timer A input (External trigger input in one-shot pulse mode)

	Symbol	Parameter	Limits	Unit	
١	Cymbol	ymbol I diameter	Min.	Max.	Unit
	tc(TA)	TAilN input cycle time	8 X 10 ⁹ 2 • f(f ₂)		ns

Timer B input (In pulse period measurement mode or pulse width measurement mode)

Symbol	Parameter	Limits	Unit
Cynnoon	1 didiriotor	Min. Max.	Offic
tc(TB)	TBiin input cycle time	8 X 10 ⁹ 2 • f(f2)	ns
tw(TBH)	ТВіін input high-level pulse width	4 X 10 ⁹ 2 • f(f ₂)	ns
tw(TBL)	TBilN input low-level pulse width	4 X 10° 2 • f(f2)	ns

Note. f(f2) represents the clock f2 frequency.

For the relation to the main clock and sub clock, refer to Table 10 in data sheet "M37735MHBXXXFP".





SWITCHING CHARACTERISTICS

(Vcc = 5 V \pm 10%, Vss = 0 V, Ta = -20 to +85°C, f(XIN) = 25 MHz, unless otherwise noted (Note))

Microprocessor mode

Symbol	Parameter	Test conditions	Lin	Unit	
Oymboi	1 drameter	rest conditions	Min.	Max.	Offic
td(WE-P4Q)	Port P4 data output delay time			80	ns
td(WE-P5Q)	Port P5 data output delay time			80	ns
td(WE-P6Q)	Port P6 data output delay time	Fig. 14		80	ns
td(WE-P7Q)	Port P7 data output delay time			80	ns
td(WE-P8Q)	Port P8 data output delay time			80	ns

Note. This applies when the main clock division selection bit = "0" and f(f2) = 12.5 MHz.

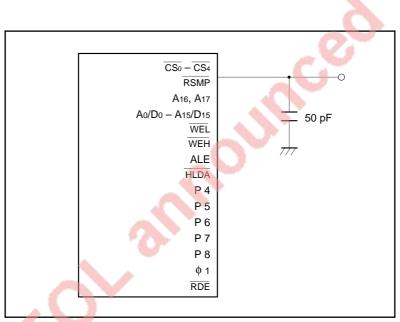


Fig. 14 Measuring circuit for each pin





Microprocessor mode

(Vcc = 5 V \pm 10%, Vss = 0 V, Ta = -20 to +85 °C, f(XIN) = 25 MHz, unless otherwise noted (Note 1))

Symbol	Parameter	(Note 2)	Test	Lir	nits	11
Symbol	Falametei	Wait mode	conditions	Min.	Max.	Unit
td(CS-WE)	Ohio ashad autod dalau fara	No wait		12		ns
td(CS-RDE)	Chip-select output delay time	Wait 1				
th(WE-CS)		Wait 0		87		ns
th(RDE-CS)	Chip-select hold time			4		ns
td(An–WE)		No wait		12		ns
td(An–RDE)	Address output delay time	Wait 1				
		Wait 0		87		ns
td(A-WE)	Address sutput delevitims	No wait		12		ns
td(A-RDE)	Address output delay time	Wait 1 Wait 0		75		ns
th(WE-An)		Wall 0				
th(RDE-An)	Address hold time			18		ns
		No wait		22		ns
tw(ALE)	ALE pulse width	Wait 1	The Party			110
		Wait 0	/ di	57		ns
t(A ALE)	Address subject setup times	No wait	Fig. 14	5		ns
tsu(A-ALE)	Address output setup time	Wait 1		45		
		Wait 0		45		ns
th(ALE-A)	Address hold time	No wait Wait 1		9		ns
	Address floid time	Wait 0	-	15		ns
		No wait				
td(ALE-WE)	ALE output delay time	Wait 1		4		ns
td(ALE-RDE)		Wait 0		10		ns
td(WE-DQ)	Data output delay time				45	ns
th(WE-DQ)	Data hold time			18		ns
		No wait		50		ns
tw(WE)	WEL/WEH pulse width	Wait 1		130		nc
	7/3	Wait 0		100		ns
tpxz(RDE-DZ)	Floating start delay time				5	ns
tpzx(RDE-DZ)	Floating release delay time			20		ns
		No wait		48		ns
tw(RDE)	RDE pulse width	Wait 1 Wait 0		128		ns
td(RSMP-WE)		1				
td(RSMP-RDE)	RSMP output delay time			10		ns
th(\$ 1-RSMP)	RSMP hold time]	0		ns
td(WE- φ 1) td(RDE- φ 1)	φ1 output delay time			0	18	ns
td(\$ 1-HLDA)	HLDA output delay time]		50	ns

Notes 1. This applies when the main clock division selection bit = "0" and $f(f_2) = 12.5$ MHz.

2. No wait : Wait bit = "1".

Wait 1: The external memory area is accessed with wait bit = "0" and wait selection bit = "1".

Wait 0 : The external memory area is accessed with wait bit = "0" and wait selection bit = "0".



Microprocessor mode

Bus timing data formulas (Vcc = 5 V ± 10%, Vss = 0 V, Ta = -20 to +85 °C, f(XIN) = 25 MHz (Max.), unless otherwise noted (Note1))

Symbol	Parameter		Limits		I India
Symbol	Falametei	Wait mode	Min.	Max.	Unit
		No wait	$\frac{1 \times 10^9}{2 \times 10^9}$ -28		ns
td(CS-WE)	Chip-select output delay time	Wait 1	Z ♥ 1(12)		115
td(CS-RDE)	only solicit delay time	Wait 0	$\frac{3 \times 10^9}{2000000000000000000000000000000000000$		ns
		waito	2 • f(f ₂) = 33		110
th(WE-CS)	Chip-select hold time		4		ns
th(RDE-CS)	'	NI==:t	4 1/ 409		
td(An–WE)		No wait Wait 1	$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 28$		ns
td(An–RDE)	Address output delay time		3 X 10 ⁹		1
ta(/iii NBL)		Wait 0	$\frac{3 \times 10}{2 \cdot f(f_2)} - 33$		ns
		No wait	1 ∨ 109		
td(A-WE)	Address submit delevities	Wait 1	$\frac{1 \times 10^{4}}{2 \cdot f(f_2)} - 28$		ns
td(A-RDE)	Address output delay time	Wait 0	$\frac{3 \times 10^9}{1000} - 45$		
		wait o	2 • f(f ₂) = 45		ns
th(WE-An)	Address hold time		1 X 10 ⁹ - 22		ns
th(RDE-An)	Address field time		2 • f(f2)		113
		No wait	$\frac{1 \times 10^9}{2000} - 18$		ns
tw(ALE)	ALE pulse width	Wait 1	2 • f(f2)		
		Wait 0	$\frac{2 \times 10^9}{2 \times 10^9} - 23$		ns
	<u> </u>	No wait	2 • f(f ₂) - 23 1 × 10 ⁹		
		Wait 1	$\frac{1 \times 10^{5}}{2 \cdot f(f_2)} - 35$		ns
tsu(A-ALE)	Address output setup time		2 X 10 ⁹		
		Wait 0	$\frac{2\times 10}{2^{\bullet} \text{ f(f2)}} - 35$		ns
		No wait	` ′		
	Address hold time	Wait 1	9		ns
th(ALE-A)	Address floid time		1 X 10 ⁹ - 25		
		Wait 0	2 • f(f ₂)		ns
		No wait	4		ns
td(ALE-WE)	ALE output delay time	Wait 1			110
td(ALE-RDE)		Wait 0	$\frac{1 \times 10^9}{200}$ - 30		ns
t 101/5 DO			2 • f(f2)	45	
td(WE-DQ)	Data output delay time		4 V 409	45	ns
th(WE-DQ)	Data hold time		$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 22$		ns
			2 × 1(12) 2 × 10 ⁹		
		No wait	$\frac{2\times10}{2 \cdot f(f_2)} - 30$		ns
tw(WE)	WEL/WEH pulse width	Wait 1	4 ¥ 109		
	· ·	Wait 0	$\frac{7 \times 10}{2 \cdot f(f_2)} - 30$		ns
tpxz(RDE-DZ)	Floating start delay time		` ,	5	ns
tpzx(RDE-DZ)	Floating release delay time		1 X 10 ⁹ - 20		nc
thex(KDE-DE)	Floating release delay time		2 • f(f2)		ns
		No wait	$\frac{2 \times 10^9}{2 \times 10^9} - 32$		ns
tw(RDE)	RDE pulse width		2 • f(f2)		
` ′	,	Wait 1	$\frac{4 \times 10^9}{2 \times 4(4x)} - 32$		ns
Avenue ···		Wait 0	2 • f(f2) - 32		
td(RSMP-WE)	RSMP output delay time		$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 30$		ns
td(RSMP-RDE) th(\$ 1-RSMP)	DOMP hald time		0		- no
$td(WE - \phi_1)$	RSMP hold time		U		ns
td(WE= \(\psi \) 1)	φ 1 output delay time		0	18	ns
***(INDE - 4 1)	1				1

Notes 1. This applies when the main clock division selection bit = "0".

2. f(f2) represents the clock f2 frequency.

For the relation to the main clock and sub clock, refer to Table 10 in data sheet "M37735MHBXXXFP".





Port P7 output

Port P7 input

Port P8 output

Port P8 input

16-BIT CMOS MICROCOMPUTER

TIMING DIAGRAM XIN $\overline{\mathsf{RDE}},\overline{\mathsf{WEL}},\overline{\mathsf{WEH}}$ td(WE-P4Q) Port P4 output $t_{su(P4D-RDE)}$ th(RDE-P4D) Port P4 input **t**d(WE−P5Q) Port P5 output $t_{\text{su}(\text{P5D-RDE})}$ th(RDE-P5D) Port P5 input < > td(WE-P6Q) Port P6 output ←→ th(RDE-P6D) $t_{\text{su}(\text{P6D-RDE})}$ Port P6 input ★ td(WE-P7Q)

 \leftrightarrow

th(RDE-P7D)

td(WE-P8Q)

←→ th(RDE-P8D)

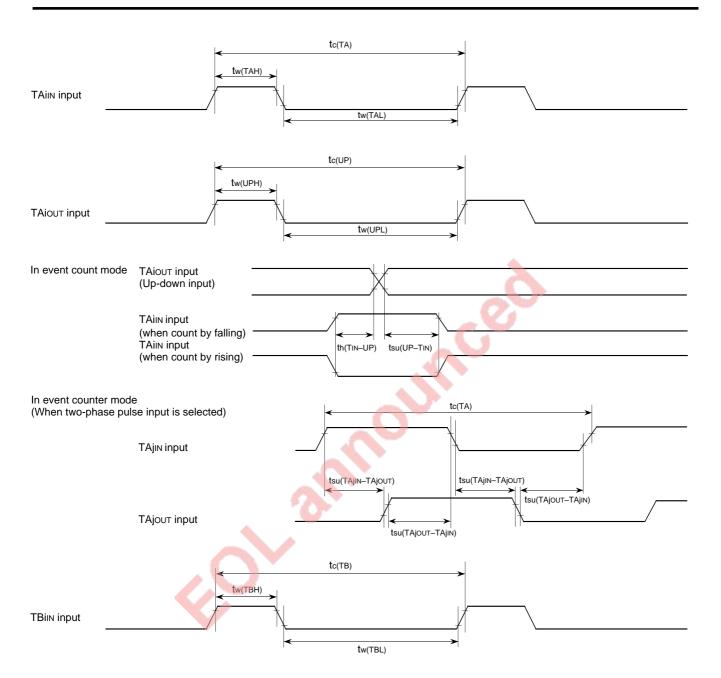
tsu(P7D-RDE)

tsu(P8D-RDE)



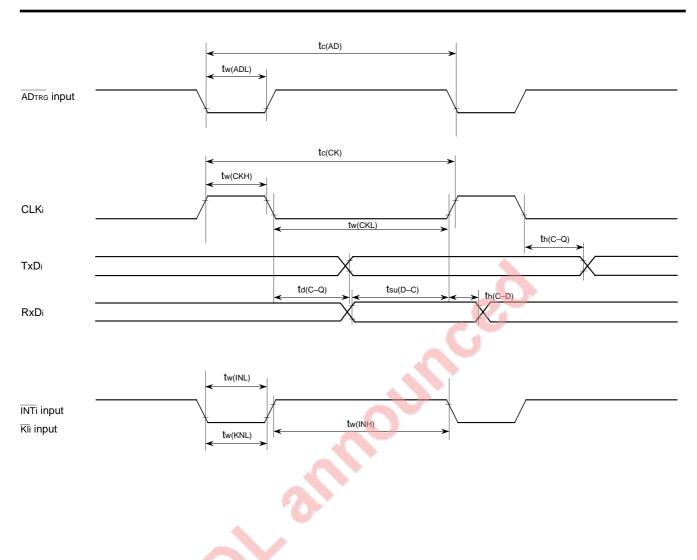


16-BIT CMOS MICROCOMPUTER

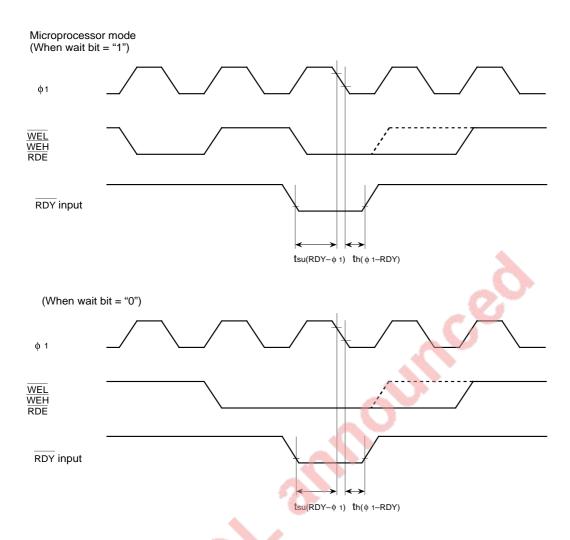




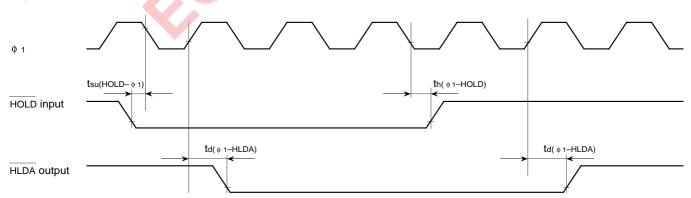








(When wait bit = "1" or "0" in common)



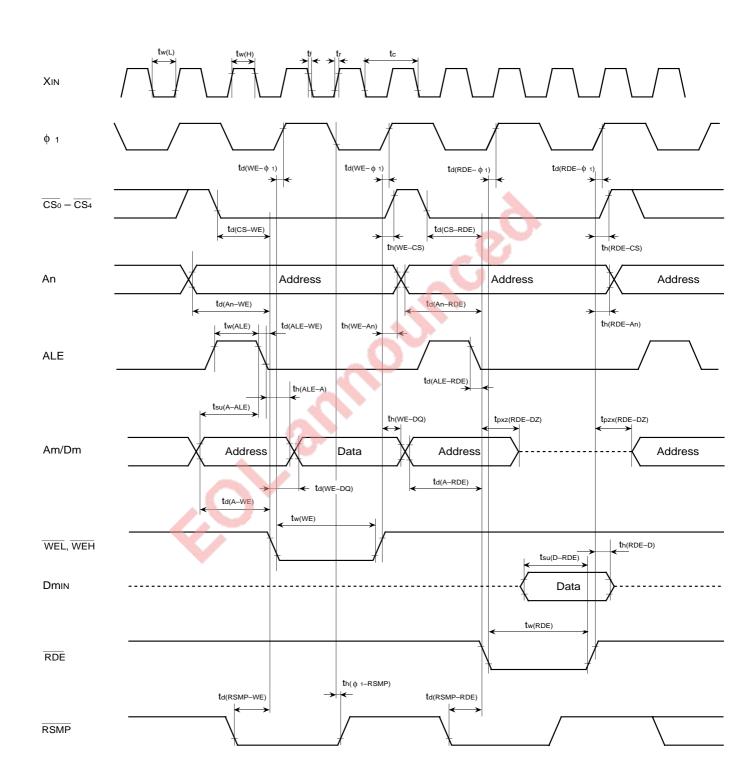
Test conditions

- Vcc = 5 V ± 10%
 Input timing voltage : VIL = 1.0 V, VIH = 4.0 V
 Output timing voltage : VoL = 0.8 V, VOH = 2.0 V





Microprocessor mode (No wait : When wait bit = "1")



Test condition

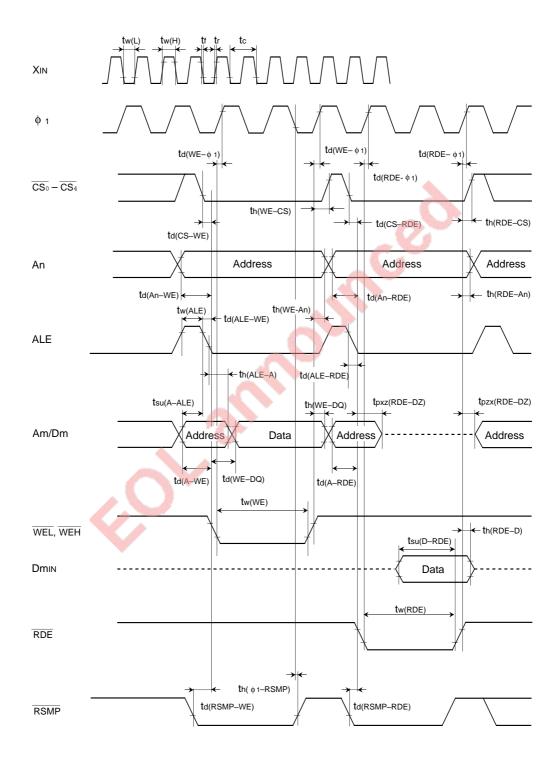
- $Vcc = 5 V \pm 10\%$
- \bullet Output timing voltage : VoL = 0.8 V, VoH = 2.0 V
- Data input Dmin : VIL = 0.8 V, VIH = 2.5 V





Microprocessor mode

(Wait 1: The external area is accessed when wait bit = "0" and wait selection bit = "1".)



Test condition

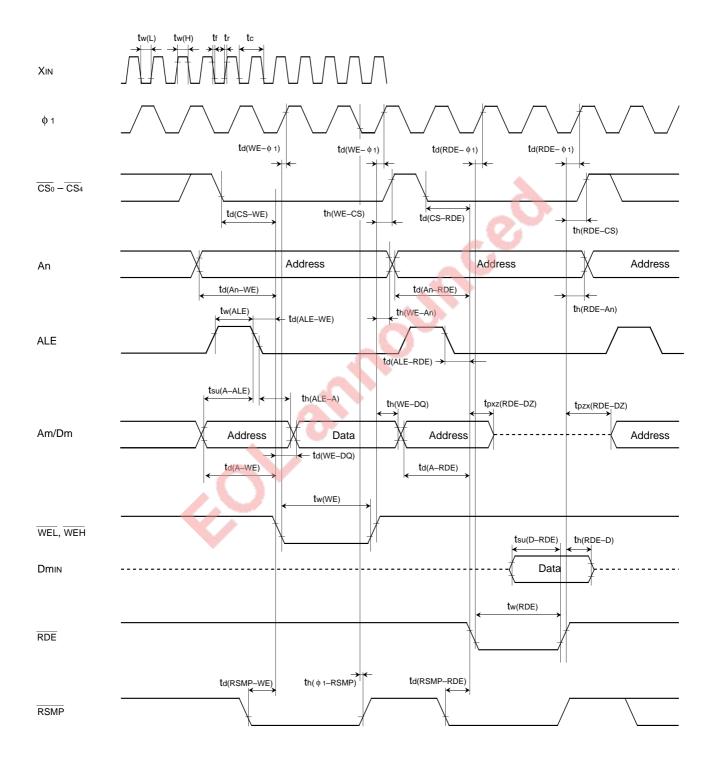
- Vcc = 5 V ± 10%
- \bullet Output timing voltage : VoL = 0.8 V, VoH = 2.0 V
- \bullet Data input DmIN : VIL = 0.8 V, VIH = 2.5 V





Microprocessor mode

(Wait 0: The external memory are is accessed when wait bit = "0" and wait selection bit = "0".)



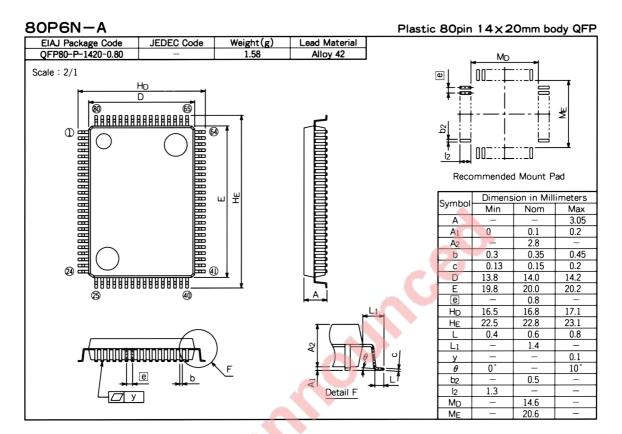
Test conditions

- Vcc = 5 V ± 10%
- \bullet Output timing voltage : VoL = 0.8 V, VoH = 2.0 V
- Data input Dmin : VIL = 0.8 V, VIH = 2.5 V





PACKAGE OUTLINE





MEMO







Renesas Technology Corp.

Nippon Bldg.,6-2,Otemachi 2-chome,Chiyoda-ku,Tokyo,100-0004 Japan

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